

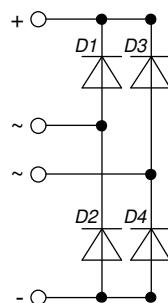
# Standard Rectifier Module

1~ Rectifier	
$V_{RRM}$	= 1200 V
$I_{DAV}$	= 25 A
$I_{FSM}$	= 370 A

## 1~ Rectifier Bridge

Part number

**VBO25-12NO2**



 E72873

### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

### Applications:

- Diode for main rectification
- For one phase bridge configurations
- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

### Package: FO-A

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- 1/4" fast-on terminals
- Easy to mount with one screw

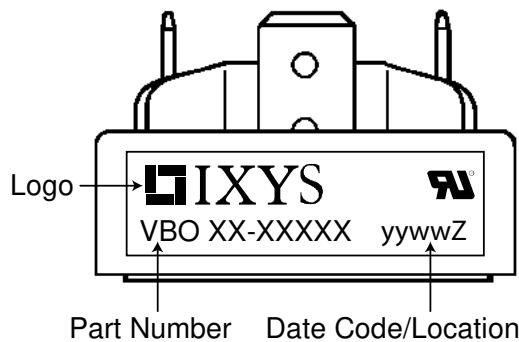
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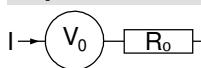
**Rectifier**

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM}$	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1300	V
$V_{RRM}$	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1200	V
$I_R$	reverse current	$V_R = 1200 \text{ V}$ $V_R = 1200 \text{ V}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		100 1	$\mu A$ mA
$V_F$	forward voltage drop	$I_F = 25 \text{ A}$	$T_{VJ} = 25^\circ C$		1.18	V
		$I_F = 50 \text{ A}$			1.37	V
		$I_F = 25 \text{ A}$	$T_{VJ} = 125^\circ C$		1.13	V
		$I_F = 50 \text{ A}$			1.37	V
$I_{DAV}$	bridge output current	$T_C = 125^\circ C$ rectangular	$T_{VJ} = 150^\circ C$ $d = 0.5$		25	A
$V_{F0}$ $r_F$	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ C$		0.88	V
					9.6	$m\Omega$
$R_{thJC}$	thermal resistance junction to case				2	K/W
$R_{thCH}$	thermal resistance case to heatsink			0.4		K/W
$P_{tot}$	total power dissipation		$T_C = 25^\circ C$		60	W
$I_{FSM}$	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		370	A
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		400	A
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$		315	A
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		340	A
$I^2t$	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		685	$A^2s$
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		665	$A^2s$
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$		495	$A^2s$
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 \text{ V}$		480	$A^2s$
$C_J$	junction capacitance	$V_R = 400 \text{ V}; f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	11		pF

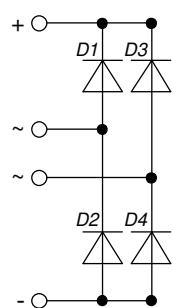
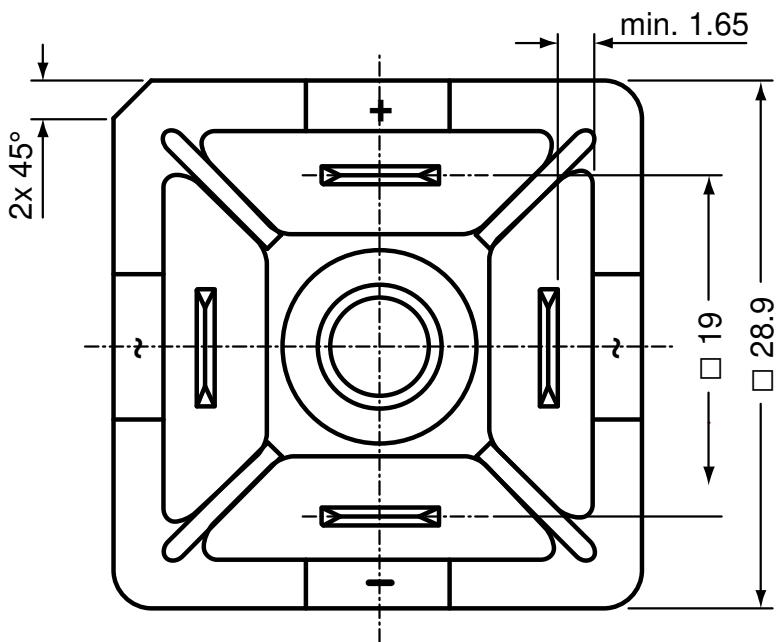
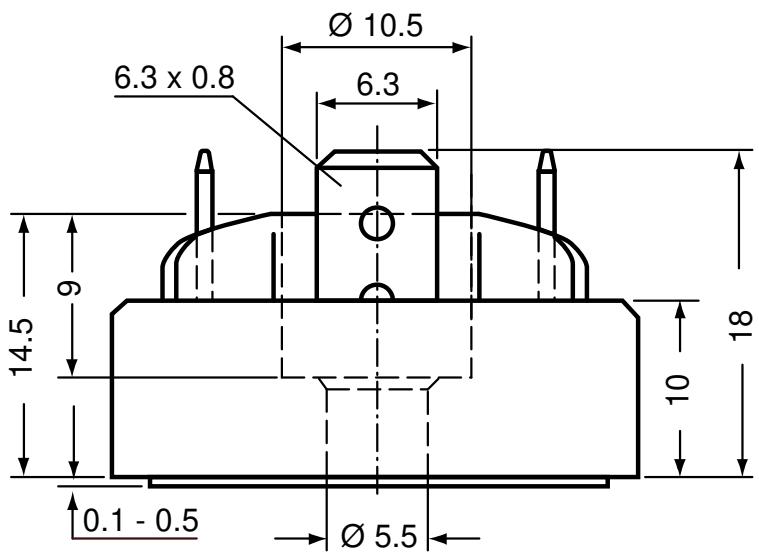
Package FO-A			Ratings		
Symbol	Definition	Conditions	min.	typ.	max.
$I_{RMS}$	RMS current	per terminal			100 A
$T_{VJ}$	virtual junction temperature		-40		150 °C
$T_{op}$	operation temperature		-40		125 °C
$T_{stg}$	storage temperature		-40		125 °C
<b>Weight</b>				15	g
$M_D$	mounting torque		1.5		2 Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air		terminal to terminal	13.0	mm
$d_{Spb/Apb}$			terminal to backside		mm
$V_{ISOL}$	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000 2500	V V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VBO25-12NO2	VBO25-12NO2	Box	10	424412

**Equivalent Circuits for Simulation**
\* on die level
 $T_{VJ} = 150^\circ\text{C}$ 

**Rectifier**

$V_{0\max}$  threshold voltage 0.88 V  
 $R_{0\max}$  slope resistance \* 8.4 mΩ

**Outlines FO-A**


## Rectifier

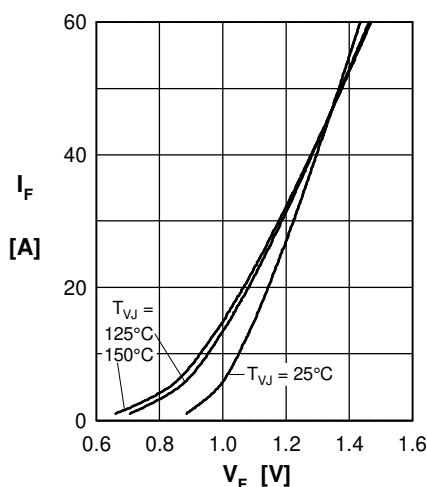


Fig. 1 Forward current vs.  
voltage drop per diode

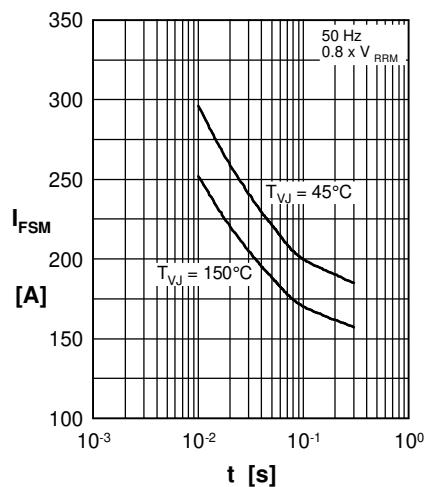


Fig. 2 Surge overload current  
vs. time per diode

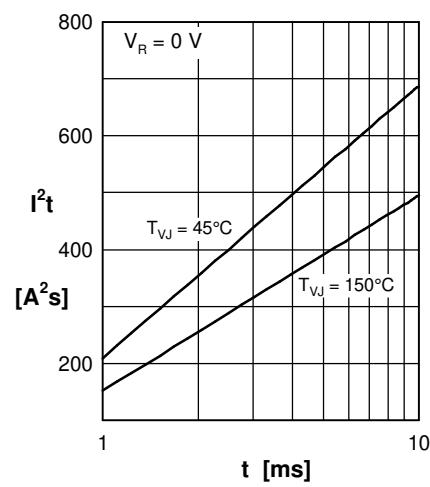


Fig. 3  $I^2t$  vs. time per diode

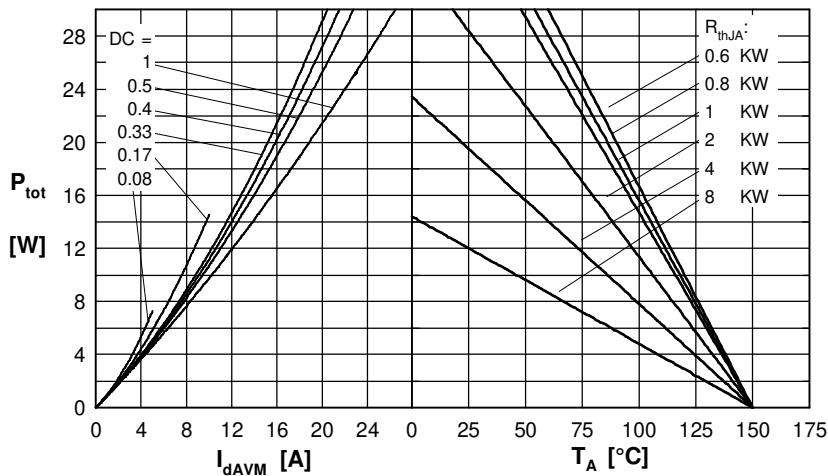


Fig. 4 Power dissipation vs. forward current  
and ambient temperature per diode

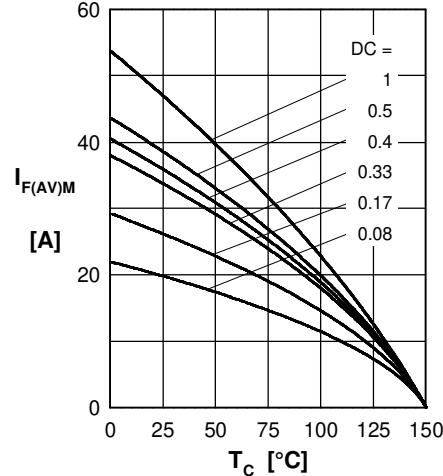


Fig. 5 Max. forward current vs.  
case temperature per diode

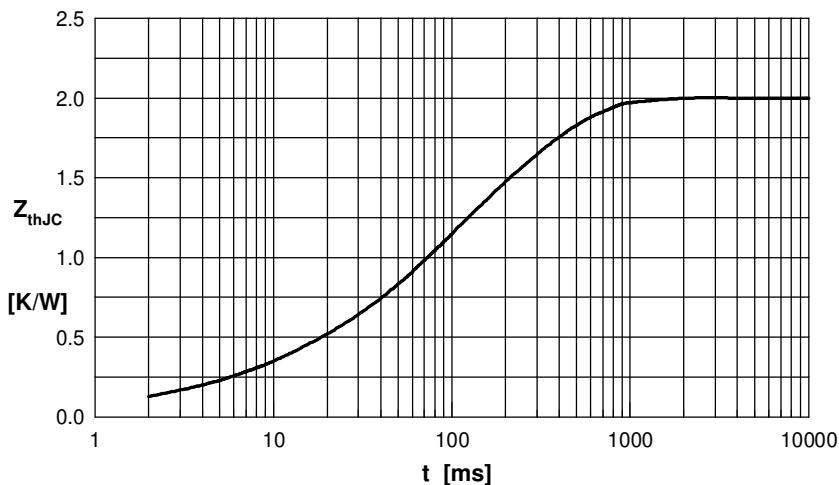


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for  $Z_{thJC}$  calculation:

i	$R_{th}$ (K/W)	$t_i$ (s)
1	0.061	0.001
2	0.203	0.008
3	0.500	0.250
4	0.703	0.060
5	0.533	0.300